#### 505119357 10/01/2018

## PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
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ALI ERAY TOPAK	08/01/2018
ARNDT THOMAS OTT	08/01/2018

### **RECEIVING PARTY DATA**

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City:	TOKYO
State/Country:	JAPAN
Postal Code:	108-0075

### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	16090219

### CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	11196US01
NAME OF SUBMITTER:	FAITH BAGGETT
SIGNATURE:	/Faith Baggett/
DATE SIGNED:	10/01/2018

#### **Total Attachments: 4**

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> **PATENT REEL: 047015 FRAME: 0175**

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PATENT REEL: 047015 FRAME: 0176

# PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT	
ASSIGNOR(S): (Insert Inventor(s) name, city/state, cour	etry of residence)
KHAN, Wasif Tanveer; Lahore (PK)	
TOPAK, Ali Eray; Den Haag (NL)	
OTT, Arndt Thomas; Stuttgart (DE)	
ASSIGNEE: (Insert Company or Assignee Name and Ad	dress)
Sony Corporation 1-7-1 Konan	
Minato-ku, Tokyo 108-0075	
Japan	
AGREEMENT  Whereas, ASSIGNOR(S) listed above, are in the second of the s	nventor(s) of an invention entitled: RATUS, PACKING AND MANUFACTURING METHOD
Application No.16/090,219 filed 29 Sep	
Assessment Communication and Assessment Asse	
with Customer No. 154930, the power to insert on th	sts ASSIGNEE'S legal representatives, of Xsensus. LLP, associated is assignment any further identification, including the application estrable in order to comply with the rules of the United States Patent int.
WHEREAS, Sony Corporation and interest in and to the Invention and in and to any in any and all foreign countries;	(ASSIGNEE), is desirous of acquiring the entire right, title letters patent that may be granted therefor in the United States and
acknowledged, ASSIGNOR(S) hereby sell, assign an right, title and interest in and to said Invention and an patent which may be granted for said Invention in the and all foreign countries, and in any and all provision including the right to file foreign applications directly from said application to which said foreign applicatio otherwise, said invention, application and all letters p its successors and assigns for their use and benefit an	and valuable consideration, the receipt of which is hereby d transfer unto ASSIGNEE its successors and assigns, the entire ly improvements thereto, said Application and any and all letters. United States of America and its territorial possessions and in any all, divisions, reissues, re-examinations and continuations thereof, in the name of ASSIGNEE and to claim priority rights deriving ans are entitled by virtue of international convention, treaty or atent on said Invention to be held and enjoyed by ASSIGNEE and dof their successors and assigns as fully and entirely as the same had this assignment, transfer and sale not been made,

PATENT REEL: 047015 FRAME: 0177 and prosecution of applications for United States and foreign letters patent on said Invention, for litigation regarding said letters patent, or for the purpose of protecting title to said Invention or letters patent therefor.

AND ASSIGNOR(S) DOES HEREBY sell, assign, transfer, and convey to ASSIGNEE, its successors, legal representatives, and assigns all claims for damages and all remedies arising out of any violation of the rights assigned hereby that may have accrued prior to the date of assignment to ASSIGNEE, or may accrue hereafter, including, but not limited to, the right to sue for, collect, and retain damages for past infringements of said letters patent before or after issuance,

AND ASSIGNOR(S) DOES HEREBY covenant and agree that ASSIGNOR(S) will communicate to said ASSIGNEE, its successors, legal representatives and assigns, any facts known to ASSIGNOR respecting the Invention or said application, and testify in any legal proceeding, assist in the preparation of any other patent document relating to the application and the Invention or any improvements made thereto, sign/execute all lawful papers, provide all requested documents, execute and make all rightful oaths and/or declarations in connection, with the application and the Invention including any improvements made thereto, any patent applications filed therefrom, and any continuing application filed from any of the aforementioned applications, and generally do everything possible to aid the ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for the Invention in the United States, its territories, and all foreign countries. These provisions are binding upon our heirs, legal representatives, administrators, and assigns.

(Signature of Inventor)	Date: Aug 7, 2018
	Date:
(Signature of Inventor)	
	Date:
(Signature of Inventor)	
	Date:
(Signature of Inventor)	
	Dute:
(Signature of inventor)	
	Date:
(Signature of Inventor)	

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AND ASSIGNOR(S) DOES HEREBY covenant and agree that ASSIGNOR(S) will communicate to said ASSIGNEE, its successors, legal representatives and assigns, any facts known to ASSIGNOR respecting the Invention or said application, and testify in any legal proceeding, assist in the preparation of any other patent document relating to the application and the Invention or any improvements made thereto, sign/execute all lawful papers, provide all requested documents, execute and make all rightful oaths and/or declarations in connection, with the application and the Invention including any improvements made thereto, any patent applications filed therefrom, and any continuing application filed from any of the aforementioned applications, and generally do everything possible to aid the ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for the Invention in the United States, its territories, and all foreign countries. These provisions are binding upon our heirs, legal representatives, administrators, and assigns.

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(Signature of Inggentm)	Aja Pisa			
		Date:	01-02	8-201
(Signature of Inventor)				
(Signature of Inventor)	38 8	Date:	2. 35 35 35 35 56 35	
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(Signature of Inventor)	**************************************			

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AND ASSIGNOR(S) DOES HEREBY covenant and agree that ASSIGNOR(S) will communicate to said ASSIGNEE, its successors, legal representatives and assigns, any facts known to ASSIGNOR respecting the Invention or said application, and testify in any legal proceeding, assist in the preparation of any other patent document relating to the application and the Invention or any improvements made thereto, sign/execute all lawful papers, provide all requested documents, execute and make all rightful oaths and/or declarations in connection, with the application and the Invention including any improvements made thereto, any patent applications filed therefrom, and any continuing application filed from any of the aforementioned applications, and generally do everything possible to aid the ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for the Invention in the United States, its territories, and all foreign countries. These provisions are binding upon our heirs, legal representatives, administrators, and assigns.

	Date:
(Signature of Inventor)	
	Date;
(Signature of Inventor)	
(Signature of Inventor)	Date: August 184 2018
(Signature of Inventor)	***************************************
	Date:
(Signature of Inventor)	***************************************
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(Signature of Inventor)	
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(Signature of Inventor)	<u>~</u>